

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	823	"174"/\$.ccls. and (resist\$3 adj layer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/02/21 16:14
L2	149	"174"/\$.ccls. and (resist\$3 adj layer) and power and ground	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/02/21 16:25
L3	188	"361"/\$.ccls. and (resist\$3 adj layer) and power and ground	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/02/21 16:37
L4	15	("4777718").URPN.	USPAT	OR	ON	2005/02/21 16:51

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File Edit View Database Help

☐ Drafts
☐ Pending
☒ Active

L1: (170) (resist\$3 adj element) and (decoupl\$3 adj capacitor) and
 L2: (15) ("5027253" or ("5261153" or ("5796587") or ("5953203
 L3: (22) Backward citation search 3
 L4: (35) 361/306.2.ccls. and resistor
 L5: (81) 361/306.3.ccls. and resistor
 L6: (156) 361/306.3.ccls. and resist\$3
 L7: (26) 361/306.3.ccls. and resistive
 L8: (111) 361/765-766.ccls. and resistive
 L9: (10) Forward citation search 2
 L10: (2) (discrete adj resistor) and (decoupling adj capacitor) and
 L11: (13) Backward citation search 4

☐ Failed
☒ Saved

S1: (114) (resist\$3 adj layer) and (decoupl\$3 adj capacitor)
 S2: (109) (resist\$3 adj layer) and (decoupl\$3 adj capacitor) and (r
 S3: (104) (resist\$3 adj layer) and (decoupl\$3 adj capacitor) and (p
 S4: (68) (resist\$3 adj layer) and (decoupl\$3 adj capacitor) and pow
 S5: (60) (resist\$3 adj component) and (decoupl\$3 adj capacitor) a
 S6: (11) Backward citation search 1
 S7: (13) Forward citation search 1
 S8: (9) Backward citation search 2

Search:

US-FOIPA/USPAT-USDOC

Date group:

("3566203" | "4744008" | "4945399" | "4949163" | "4984065" | "4994895" | "5049979" | "5055966" |
 "5119172" | "5148265" | "5148266" | "5281846" | "5311057").PN

	U	I	Document ID	Issue Date	Pages	Title	Current OR	Current XRef	Retrieval Clas	Inventor
1	<input type="checkbox"/>	<input type="checkbox"/>	US 5311057 A	19940510	8	Lead-on-chip semiconductor device and method for making the same	257/676	257/677; 257/691;		McShane, Michael B.
2	<input type="checkbox"/>	<input type="checkbox"/>	US 5281846 A	19940125	4	Electronic device having a discrete capacitor adherently mounted to a lead	257/528	257/532; 257/676;		Kaiser, Ulrich
3	<input type="checkbox"/>	<input type="checkbox"/>	US 5148266 A	19920915	19	Semiconductor chip assemblies having interposer and flexible lead	257/773	257/668; 257/669;		Khandros, Igor Y. et al.
4	<input type="checkbox"/>	<input type="checkbox"/>	US 5148265 A	19920915	28	Semiconductor chip assemblies with fan-in leads	257/773	257/668; 257/669;		Khandros, Igor Y. et al.
5	<input type="checkbox"/>	<input type="checkbox"/>	US 5119172 A	19920602	8	Microelectronic device package employing capacitively coupled	257/684	257/659; 257/E23.144		Cho, Frederick Y. et al.
6	<input type="checkbox"/>	<input type="checkbox"/>	US 5055966 A	19911008	7	Via capacitors within multi-layer, 3 dimensional structures/substrates	361/321.3	174/52.4; 257/774;		Smith, Hal D. et al.
7	<input type="checkbox"/>	<input type="checkbox"/>	US 5049979 A	19910917	12	Combined flat capacitor and lab integrated circuit chip and method	257/723	257/764; 257/916;		Hashemi, Seyed H. et al.
8	<input type="checkbox"/>	<input type="checkbox"/>	US 4994895 A	19910219	24	Hybrid integrated circuit package structure	257/791	257/874; 257/684;		Matsuzaki, Toshio et al.

☒ Help ☐ Database ☐ RTAC

257/676 257/677 257/691 257/528 257/532 257/676 257/773 257/668 257/669 257/684 257/659 257/E23.144 361/321.3 174/52.4 257/774 257/723 257/764 257/916 257/791 257/874 257/684

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